

Confirmation of impedance and stack structure

Production model 08C123393A0
















Finished board thickness 2.2(+0.22/-0.22)mm

sheet metal IT-180A

Laminated thickness 2.12±0.1mm

Customer Type

Overlay information

Nb	Stack-Up	Material	Parameter	CTL	Thickness(mm)
L1			1.5_PT_2 OZ		0.071
		PP IT180P	1080(64%)*2-106(72%)*2		0.221
L2			4 OZ	78%	0.14
		Core IT-180A	0.1mm(Exclude Copper)		0.1
L3			4 OZ	68%	0.14
		PP IT180P	1080(64%)*4		0.212
L4			4 OZ	69%	0.14
		Core IT-180A	0.1mm(Exclude Copper)		0.1
L5			4 OZ	71%	0.14
		PP IT180P	1080(64%)*4		0.215
L6			4 OZ	68%	0.14
		Core IT-180A	0.1mm(Exclude Copper)		0.1
L7			4 OZ	78%	0.14
		PP IT180P	1080(64%)*2-106(72%)*2		0.221
L8			1.5_PT_2 OZ		0.071

Remark:	
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Note We will strictly in compliance with client's design and requirements for PCB fabrication, will pay close attention to the key factors that affect the impedance such as trace width, trace space, copper thickness and dielectric thickness during the manufacturing process. But JFG is not responsible for any impedance mismatch due to layout design or components.